INVENTORS NAME: Michael O'Connor et al.

Dkt #: 884.398US2

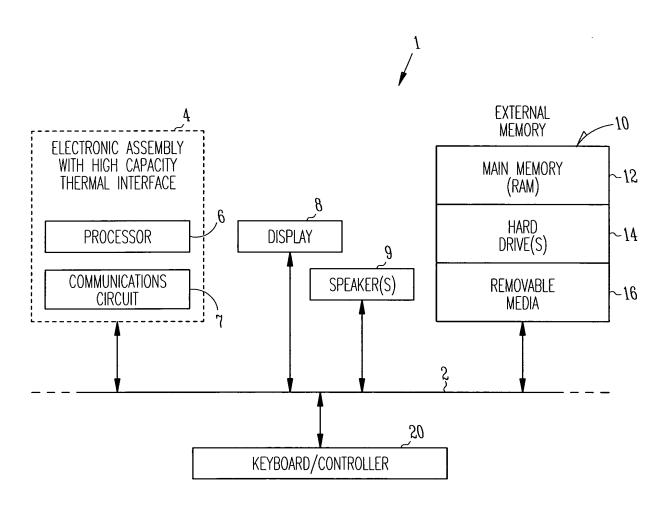
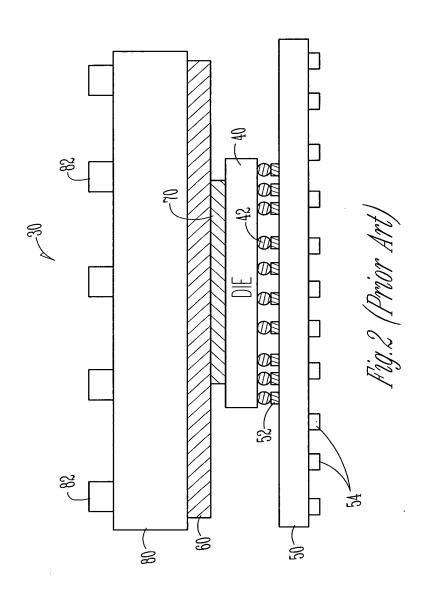


Fig. 1

TITLE: DIAMOND HEAT SPREADING AND COOLING TECHNIQUE FOR INTEGRATED CIRCUITS INVENTORS NAME: Michael O'Connor et al.

Dkt #: 884.398US2



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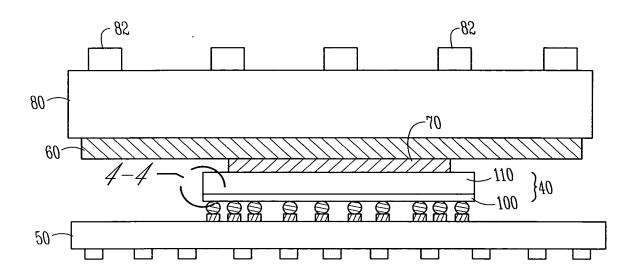


Fig.3a

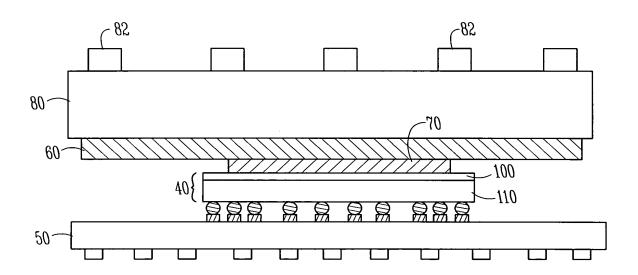


Fig. 3b

INVENTORS NAME: Michael O'Connor et al.

Dkt #: 884.398US2

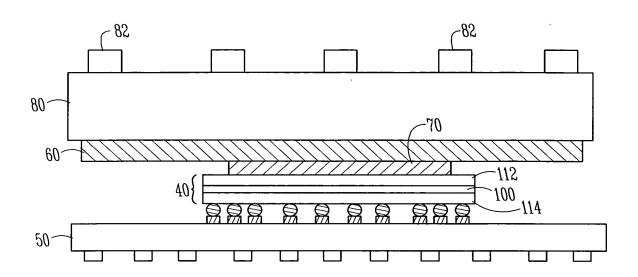
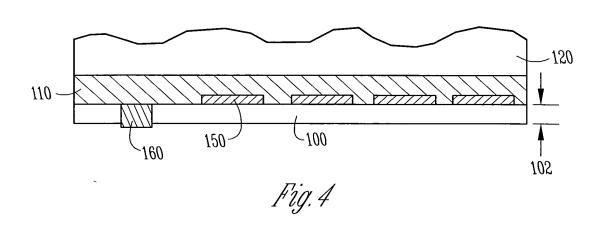


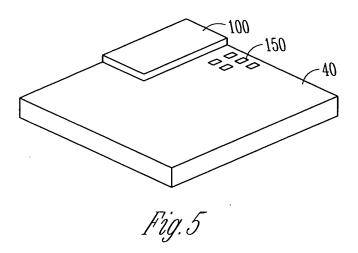
Fig.3c

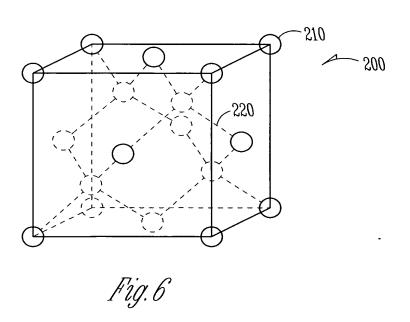


TITLE: DIAMOND HEAT SPREADING AND COOLING TECHNIQUE FOR INTEGRATED CIRCUITS INVENTORS NAME: Michael O'Connor et al.

Dkt #: 884.398US2

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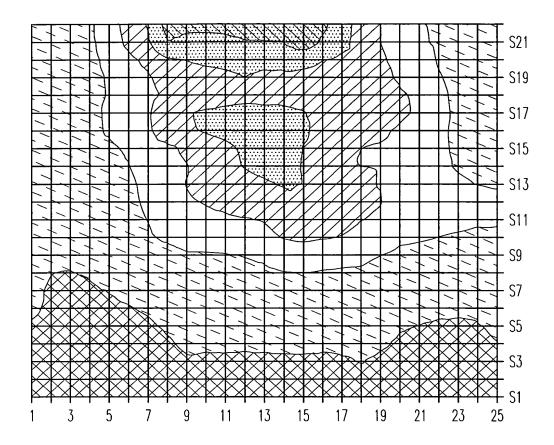


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Dkt #: 884.398US2

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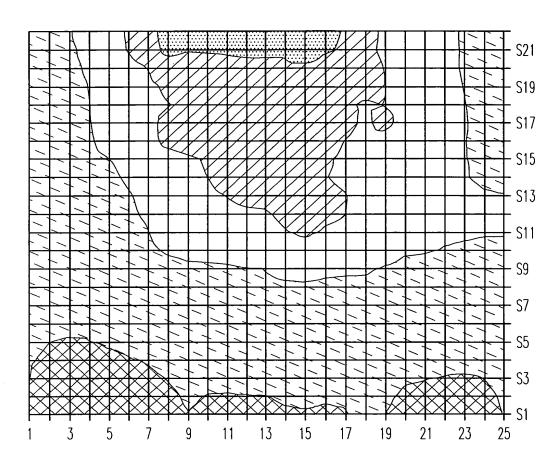


100-110 90-100 80-90 70-80 60-70 50-60 DEGREES C

INVENTORS NAME: Michael O'Connor et al.

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90-100

80-90

70-80

60-70

50-60

DEGREES C